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Cleaving Substrates for Photonics Technologies - New Downsizing Methods for Glass and Sapphire

LatticeGear designs, manufactures, and sells cleanroom compatible benchtop tools for downsizing a wide variety of substrates, both crystalline and amorphous, including silicon, GaAs, InP, sapphire, and glass. When developing tools and processes, we learned that scribing parameters such as scribe angle and depth are critical to the quality of the cleave. For crystalline materials, one must understand the crystal structure to predict the cleaving behavior. For all materials, substrate thickness, and hardness will influence the method chosen for scribing and cleaving. With this knowledge, LatticeGear developed a suite of scribing and cleaving tools that are flexible, yet also enable repeatable processes. Solutions are customized for the wide variety of materials and desired outcomes. The following describes our learning to date on thick glass, thin glass, fused quartz glass, and tempered glass. This white paper describes our learning to date on thick glass, thin glass, fused quartz glass, and tempered glass.

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